

RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

# **Data sheet**

BAW filter WLAN 2G

Series/type: B8883

Ordering code: B39242B8883L210

Date: June 26, 2019

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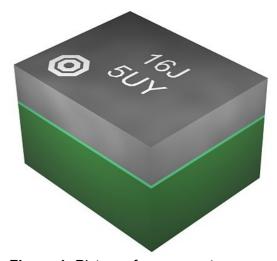
# RF360 Europe GmbH A Qualcomm – TDK Joint Venture

## 1 Application

- Ultra low-loss BAW RF single filter for Bluetooth/WLAN applications in smartphones with LTE coexistence
- Excellent insertion attenuation
- High out of band selectivity
- Unbalanced to unbalanced operation
- Filter impedance 50  $\Omega$
- Ultra small size 0907 4-pin package
- Excellent linearity

#### 2 Features

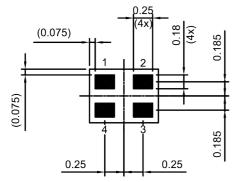
- Package size 0.9 mm × 0.7 mm
- Package height 0.6 mm
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)



**Figure 1:** Picture of component with example of product marking.

# 3 Package

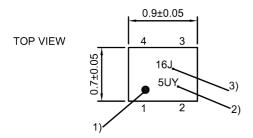
#### **BOTTOM VIEW**



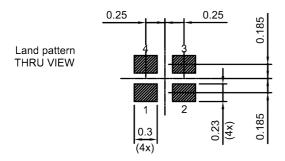
Pad and Pitch Tolerance ±0.05

#### SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



**Figure 2:** Drawing of package with package height A = 0.7 mm (max.). See Sec. Package information (p. 18).

# 4 Pin configuration

- 1 Input (to PA (unbalanced))
- 3 Output (to ANT (unbalanced))
- 2, 4 Ground

# 5 Matching circuit

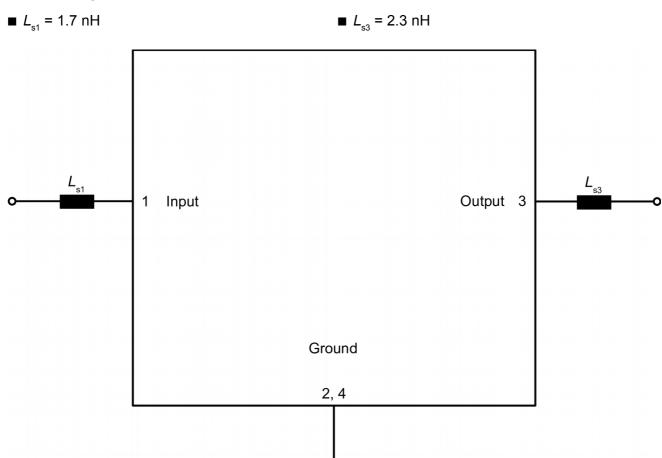


Figure 3: Schematic of matching circuit.



#### 6 Characteristics

Temperature range for specification  $T_{\rm SPEC} = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C}$  Input terminating impedance  $Z_{\rm IN} = 50~\Omega + 1.7~{\rm nH^{1)}}$  Output terminating impedance  $Z_{\rm OUT} = 50~\Omega + 2.3~{\rm nH^{1)}}$ 

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	2442	_	MHz
Insertion loss – WLAN			α				
Channel 1	2403.1 2420.9	MHz		_	1.1 <sup>2)</sup>	1.72)	dB
Channel 2	2408.1 2425.9	MHz		_	1.02)	1.72)	dB
Channel 3-10	2413.1 2465.9	MHz		_	0.92)	1.72)	dB
Channel 11	2453.1 2470.9	MHz		_	1.1 <sup>2)</sup>	1.72)	dB
Channel 12	2458.1 2475.9	MHz		_	1.22)	2.02)	dB
Channel 13	2463.1 2480.9	MHz		_	1.42)	2.22)	dB
Insertion loss – Bluetooth			α				
Channel 0-39	2401.5 2440.5	MHz		_	1.73)	3.2 <sup>3)</sup>	dB
Channel 40-78	2440.5 2480.5	MHz		_	2.03)	$3.9^{3)}$	dB
VSWR							
@ input port	2403.1 2480.9	MHz		_	1.5	2.3	
@ output port	2403.1 2480.9	MHz		_	1.5	2.3	
Attenuation			α				
	100 1805	MHz		28	31	_	dB
	1805 2170	MHz		28	31	_	dB
	2300 2360	MHz		424)	45 <sup>4)</sup>	_	dB
	2360 2365	MHz		464)	494)	_	dB
	2365 2370	MHz		464)	56 <sup>4)</sup>	_	dB
	2370 2380	MHz		15 <sup>4)</sup>	58 <sup>4)</sup>	_	dB
	2496 2501	MHz		16.54), 5)	334)	_	dB
	2500 2510	MHz		344), 5)	524)	_	dB
	2510 2540	MHz		404)	434)	_	dB
	2540 2570	MHz		324)	364)	_	dB
	2570 2690	MHz		304)	334)	_	dB
	4800 5805	MHz		35	42	_	dB
	7200 7500	MHz		30	42	_	dB

<sup>&</sup>lt;sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>&</sup>lt;sup>2)</sup> Averaged values of linear S-parameter over any 17.8 MHz.

<sup>3)</sup> Averaged value within each Bluetooth channel width of 1 MHz.

<sup>&</sup>lt;sup>4)</sup> Averaged values of linear S-parameter over any 5 MHz.

<sup>&</sup>lt;sup>5)</sup> +25°C to +85°C.



#### 7 **Maximum ratings**

Storage temperature	$T_{\text{STG}}^{2)} = -40 ^{\circ}\text{C} +85 ^{\circ}\text{C}^{1)}$	
DC voltage	$ V_{DC}  = 5.0 \text{ V}^{6)}$	
ESD voltage		
	$V_{\rm ESD}^{3)} = 50 \text{ V (max.)}$	Machine model.
	V <sub>ESD</sub> <sup>4)</sup> = 300 V	Human body model.
	V <sub>ESD</sub> <sup>5)</sup> = 600 V	Charged device model.
Input power @ input port: 2403.1 2480.9 MHz	P <sub>IN</sub> = 26 dBm	19 MHz WLAN signal for 5000 h @ 65 °C.

Extended upper limit: 96h@125°C acc. to IEC60068-2-2 Bb.

<sup>2)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>3)</sup> 

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses. According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. 4)

According to JESD22-C101C (CDM - Field Induced Charged Device Model), 3 negative & 3 positive pulses.

<sup>168</sup>h Damp Heat Steady State acc. to IEC60068-2-67 Cy.

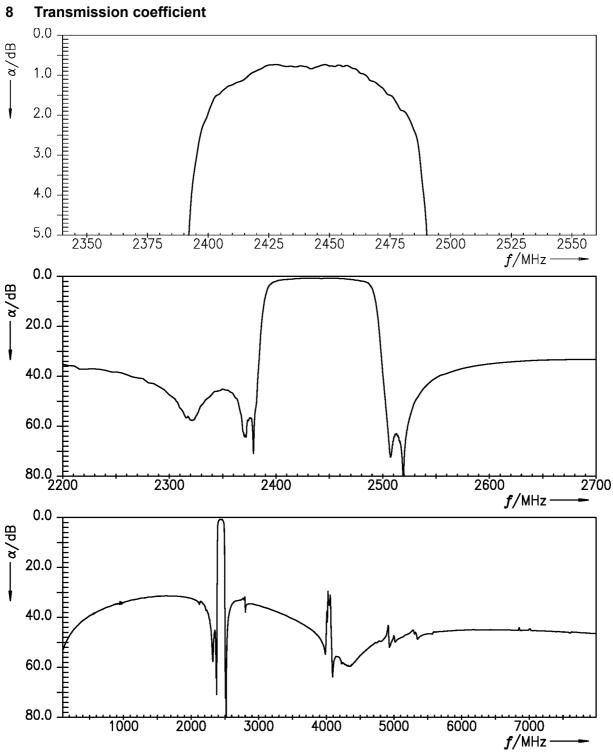
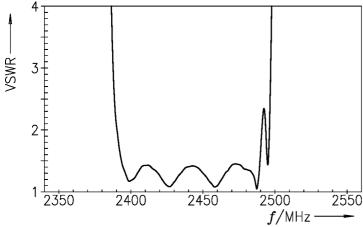


Figure 4: Attenuation.

## 9 Reflection coefficients



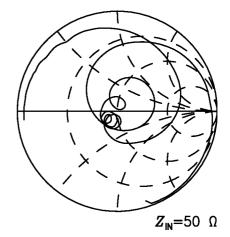
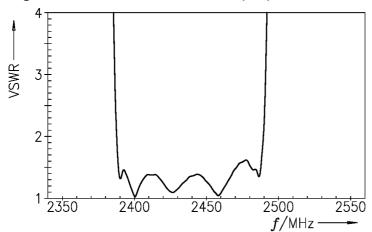


Figure 5: Reflection coefficient at input port.



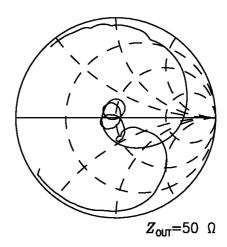
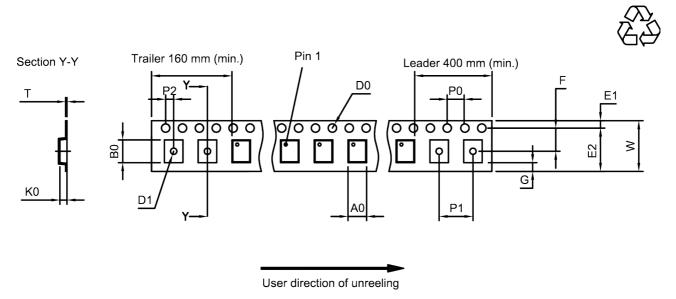


Figure 6: Reflection coefficient at output port.

# 10 Packing material

# 10.1 Tape



**Figure 7:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

<b>A</b> <sub>0</sub>	0.85±0.05 mm	E <sub>2</sub>	0.625 mm (min.)	P <sub>1</sub>	2.0±0.05 mm
B <sub>0</sub>	1.05±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
$D_0$	1.5	G	0.75 mm (min.)	T	0.25±0.02 mm
D <sub>1</sub>	0.4±0.05 mm	K <sub>0</sub>	0.69±0.03 mm	W	8.2±0.1 mm
E <sub>1</sub>	1.75 <sub>±0.1</sub> mm	P <sub>0</sub>	4.0±0.1 mm		

Table 1: Tape dimensions.

#### 10.2 Reel with diameter of 180 mm

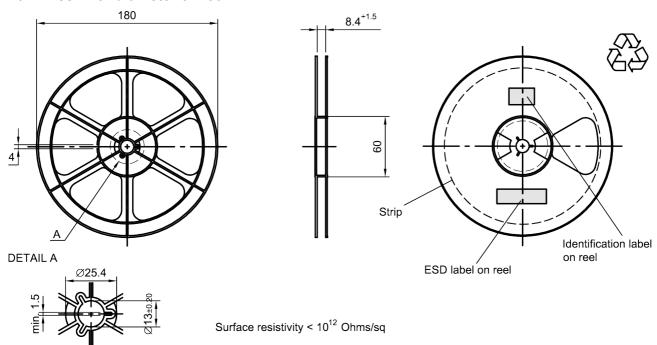


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

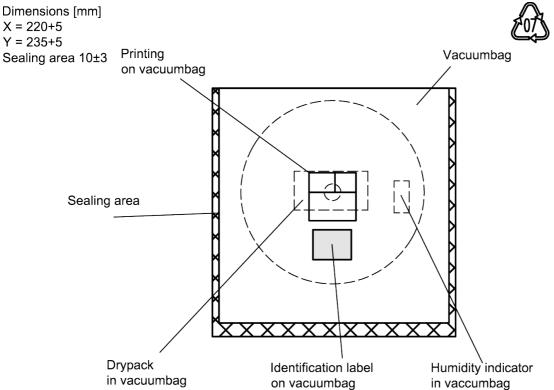


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

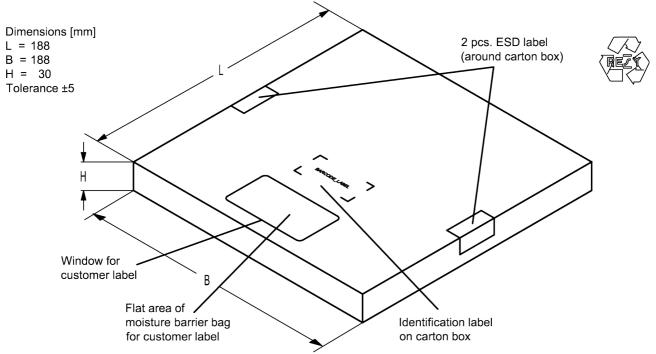
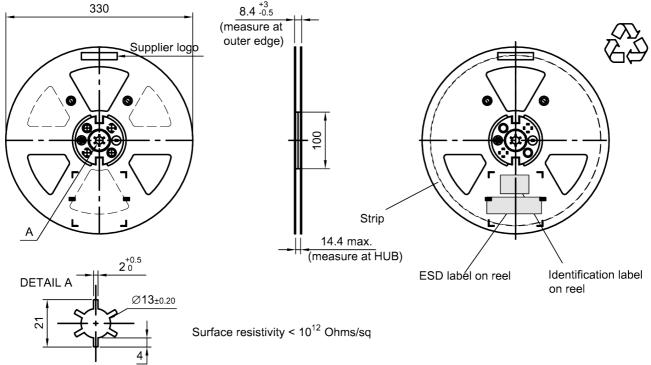


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

## 10.3 Reel with diameter of 330 mm



**Figure 11:** Drawing of reel (first-angle projection) with diameter of 330 mm.

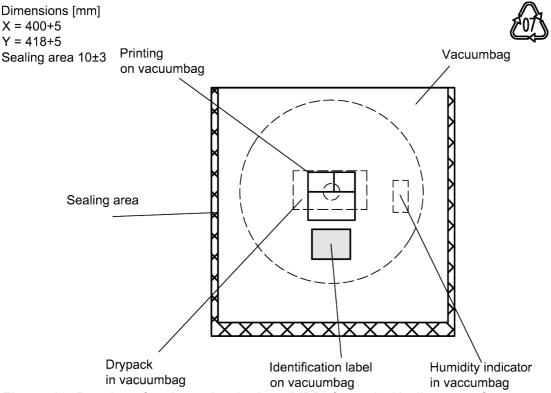


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

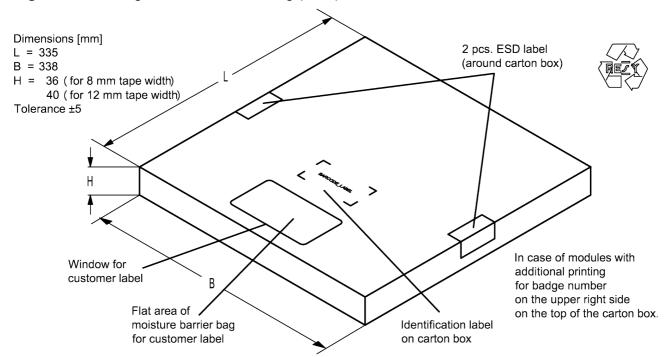


Figure 13: Drawing of folding box for reel with diameter of 330 mm.

## 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

## ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B8883 is 8NK.

#### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345  $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	M	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	Х	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	Х	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	V	
17	Н	41	\	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	М	45	<	
22	Ν	46	>	
23	Р			

**Table 2:** Lists for encoding and decoding of marking.

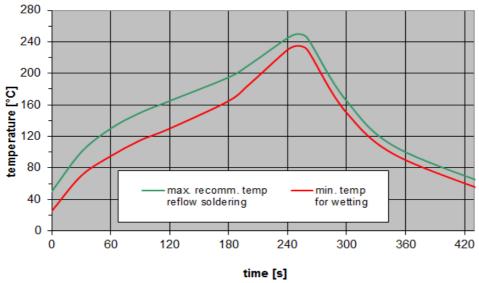


# 12 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature $T_{\text{peak}}$	250 °C +0/-5 °C
wetting temperature $T_{\min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

#### 13 Annotations

## 13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

## 13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

# 13.3 Ordering codes and packing units

Ordering code	Packing unit
B39242B8883L210	15000 pcs
B39242B8883L210S 5	5000 pcs

Table 4: Ordering codes and packing units.

## 14 Cautions and warnings

## 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.rf360jv.com/orderingcodes">www.rf360jv.com/orderingcodes</a>.

#### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

#### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

## 14.4 Package information

## Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



#### 15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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- 3. The warnings, cautions and product-specific notes must be observed.
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